

Application No. 10/788,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

Docket No. CM06657LL

REMARKS/ARGUMENTS

Claims 2 and 3 have been canceled without prejudice or disclaimer. No new matter has been added. Claims 1 and 4-7 remain in the application.

Election/Restrictions

Applicants affirm the election of Group 1, claims 1 and 4-7, without traverse. Claims 2 and 3 have been withdrawn.

Rejection - 35 U.S.C. § 102(e)

Claims 1-9, 11-20 were rejected under 35 U.S.C. § 102(e) as being anticipated by US 6,207,475 (Lin).

Applicants respectfully traverse this rejection. Prior art is anticipatory only if *every element* of the claimed invention is disclosed in a single item of prior art in the form literally defined in the claim. There must be no differences whatsoever between the claimed subject matter and the prior art in order for a Section 102 rejection to be proper. The Examiner referred to FIG. 5, items (48) and (84), col. 10, lines 12-32 and col. 10, lines 10-65 of Lin. Items (48) are solder balls and item (84) is an underfill material. Applicants were not entirely clear but are assuming that the Examiner is equating the underfill material (84) of Lin to Applicants' claimed adhesive material, and that the Examiner is also equating the solder balls (48) of Lin to Applicants' claimed solid solder element. Applicants assert that the items of Lin are not equivalent in form or functionality to that which is claimed. Underfill is used to fill the gap (or standoff) between a printed circuit board and a silicon chip.

Claim 1 recites, the adhesive material immobilizing the solid solder element during reflow. The underfill (84) of Lin does not immobilize the solder ball (48).

Application No. 10/788,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

Docket No. CM06657LL

Claim 4 recites an adhesive material for coupling the solid solder element to the solderable substrate. The underfill (84) of Lin does not couple the solder ball (48) to the substrate (56). Also, the underfill (84) of Lin does not couple the solder ball (48) to IC die (44).

Claim 7 recites an adhesive material having predetermined geometry and adhesive properties cured so as to couple the solid solder element to the solderable substrate. Here again, the underfill (84) of Lin does not couple the solder ball (48) to the substrate (56). The underfill of Lin does not couple the solder ball to the IC (44) either.

Since the cited art does not teach or suggest that which is claimed in the present application, Applicants respectfully request that the rejection be withdrawn.

Accordingly claims 1, 4 and 7 are believed to be in condition for allowance. Claims 5 and 6 provide further limitations to what is believed to be an allowable claim 4 and hence are also in condition for allowance.

No amendment made was related to the statutory requirements of patentability unless expressly stated herein. No amendment made was for the purpose of narrowing the scope of any claim, unless Applicant has argued herein that such amendment was made to distinguish over a particular reference or combination of references.

The Applicants believe that the subject application, as amended, is in condition for allowance. Such action is earnestly solicited by the Applicants.

In the event that the Examiner deems the present application non-allowable, it is requested that the Examiner telephone the Applicant's attorney or agent at the number indicated below so that the prosecution of the present case may be advanced by the clarification of any continuing rejection.

Application No. 10/786,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

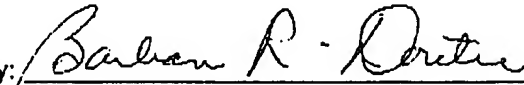
Docket No. CM06857LL

The Commissioner is hereby authorized to charge Deposit Account 502117, Motorola, Inc, with any fees which may be required in the prosecution of this application.

Respectfully submitted,

October 17, 2005

Motorola, Inc.
8000 West Sunrise Boulevard
Law Department - MD1610
Plantation, Florida 33322
Customer Number: 24273
Attachments:

By: 
Barbara R. Doutre
Reg. No.: 39,505
Tel: 954-723-6449
Fax: 954-723-3871
E-Mail: Barbara.Doutre@Motorola.com